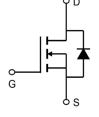


Description

The AP7N50D is silicon N-channel Enhanced

VDMOSFETs, is obtained by the self-aligned planar Technology which reduce the conduction loss, improve switching performance and enhance the avalanche energy. The transistor can be used in various power switching circuit for system miniaturization and higher efficiency.



General Features

 $V_{DS} = 500V I_{D} = 7A$

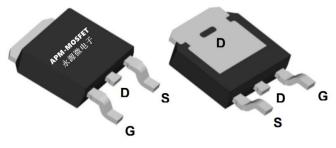
 $R_{DS(ON)} < 1.5\Omega$ @ $V_{GS}=10V$ (Type: 1.2Ω)



Application

Uninterruptible Power Supply(UPS)

Power Factor Correction (PFC)



Package Marking and Ordering Information

	<u> </u>		
Product ID	Pack	Marking	Qty(PCS)
AP7N50D	TO-252-3L	AP7N50D XXX YYYY	2500

Absolute Maximum Ratings (T_c=25°C unless otherwise noted)

Symbol	Parameter	Value	Unit
VDSS	Drain-Source Voltage (V _{GS} = 0V)	500	V
ID	Continuous Drain Current	7	А
IDM	Pulsed Drain Current (note1)	28	А
VGS	Gate-Source Voltage	±30	V
Eas	Single Pulse Avalanche Energy (note2)	247	mJ
IAR	Avalanche Current (note1)	7	Α
Ear	Repetitive Avalanche Energy note1)	18	mJ
P _D	Power Dissipation (T _C = 25°C)	32.9	W
TJ, Tstg	Operating Junction and Storage Temperature Range	-55~+150	°C
RthJC	Thermal Resistance, Junction-to-Case	3.8	°C/W
RthJA	Thermal Resistance, Junction-to-Ambient	13.3	°C/W





Electrical Characteristics (T_J=25°C, unless otherwise noted)

Symbol	Parameter Test Conditions		Min	Тур	Max	Unit
V(BR)DSS	Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D = 250μA		550		V
IDSS	Zero Gate Voltage Drain Current	V _{DS} = 650V, V _{GS} = 0V, T _J =25°C			1	μΑ
IGSS	Gate-Source Leakage	V _{GS} = ±30V			±100	nA
VGS(th)	Gate-Source Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250 \mu A$	2.0		4.0	V
RDS(on)	Drain-Source On-Resistance (Note3)	V _{GS} = 10V, I _D = 3.5A		1.2	1.5	Ω
C _{iss}	Input Capacitance			700		
Coss	Output Capacitance	$V_{GS} = 0V$, $V_{DS} = 25V$, $f = 1.0MHz$		94		pF
Crss	Reverse Transfer Capacitance			12		
Qg	Total Gate Charge			19		
Q _{gs}	Gate-Source Charge	V_{DD} =520V, I_D = 7A, V_{GS} = 10V		3.7		nC
Q_{gd}	Gate-Drain Charge			11		
td(on)	Turn-on Delay Time			13		
t _r	Turn-on Rise Time	V_{DD} =325V, I_D = 7A, R_G = 25 Ω		20		
td(off)	Turn-off Delay Time	VDD-323V, ID - /A, RG - 2312		76		ns
t _f	Turn-off Fall Time			40		
IS	Continuous Body Diode Current	T _C = 25 °C			7.0	Α
ISM	Pulsed Diode Forward Current	10 - 20 0			28	Α
V _{SD}	Body Diode Voltage	$T_J = 25^{\circ}C$, $I_{SD} = 7A$, $V_{GS} = 0V$			1.4	V
trr	Reverse Recovery Time	V _{GS} = 0V,I _S = 7A, di _F /dt =100A		260		ns
Q _{rr}	Reverse Recovery Charge	/µs		3.8		μC

Note:

- 1. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.
- 2. The EAS data shows Max. rating . IAS = 4.5A, VDD = 50V, RG = 25 Ω , Starting TJ = 25 $^{\circ}$ C
- 3、The test condition is Pulse Test: Pulse width ≤ $300\mu s$, Duty Cycle ≤ 1%
- 5、The data is theoretically the same as ID and IDM, in real applications, should be limited by total power dissipation.



Typical Characteristics

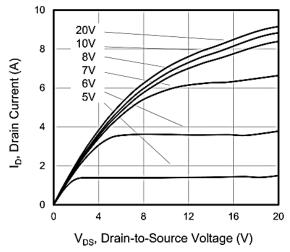


Figure 1. Output Characteristics (T J = 25°C)

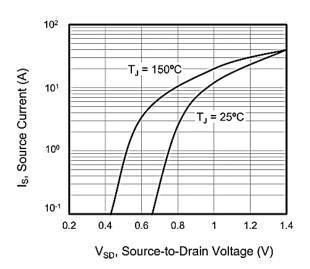


Figure 2. Body Diode Forward Voltage

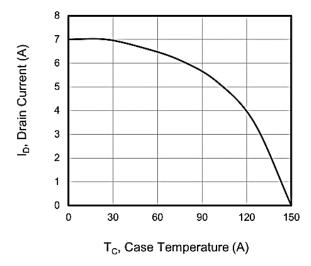


Figure 3. Drain Current vs. Temperature

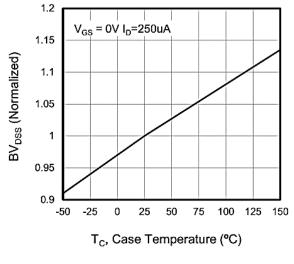


Figure 4. BV DSS Variation vs. Temperature

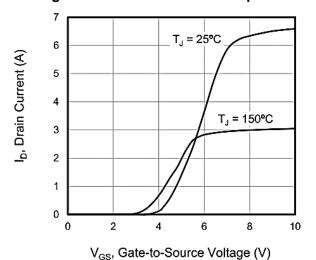
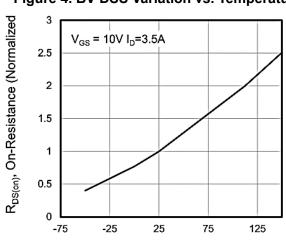


Figure 5. Transfer Characteristics

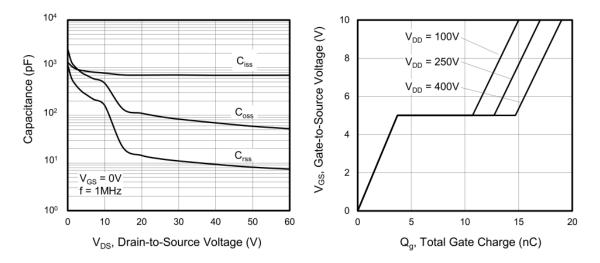


T_J, Junction Temperature (°C)

Figure 6. On-Resistance vs. Temperature









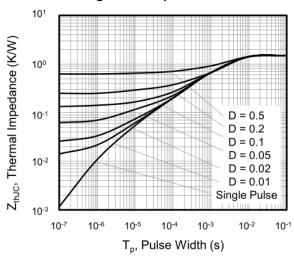
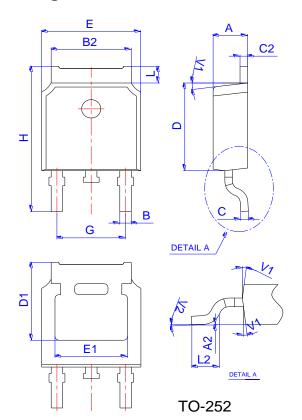


Figure 9. Transient Thermal Impedance

Figure 8. Gate Charge

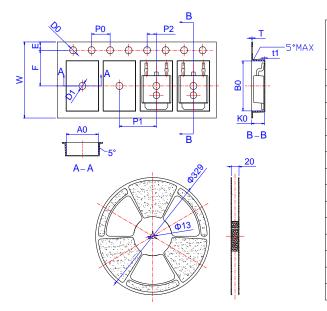


Package Mechanical Data



	Dimensions					
Ref.	Millimeters		Inches			
	Min.	Тур.	Max.	Min.	Тур.	Max.
Α	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
В	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
С	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
Н	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

Reel Spectification-TO-252



	Dimensions					
Ref.	Millimeters			Inches		
	Min.	Тур.	Max.	Min.	Тур.	Max.
W	15.90	16.00	16.10	0.626	0.630	0.634
Е	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
D0	1.40	1.50	1.60	0.055	0.059	0.063
D1	1.40	1.50	1.60	0.055	0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
A0	6.85	6.90	7.00	0.270	0.271	0.276
В0	10.45	10.50	10.60	0.411	0.413	0.417
K0	2.68	2.78	2.88	0.105	0.109	0.113
T	0.24		0.27	0.009		0.011
t1	0.10			0.004		
10P0	39.80	40.00	40.20	1.567	1.575	1.583



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Edition	Date	Change
Rve1.0	2021/1/31	Initial release

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